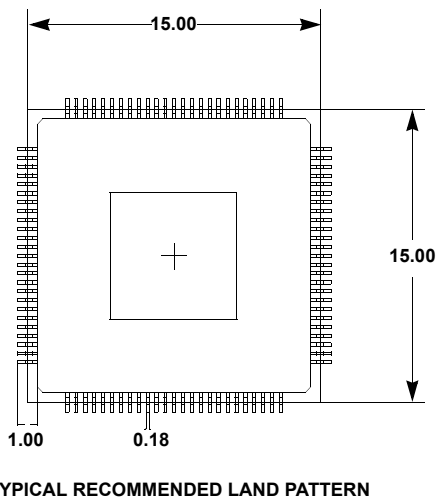
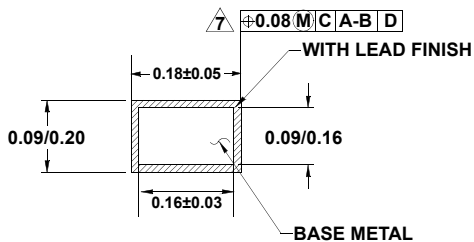
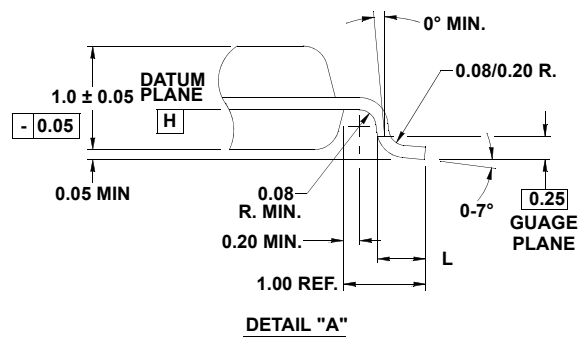
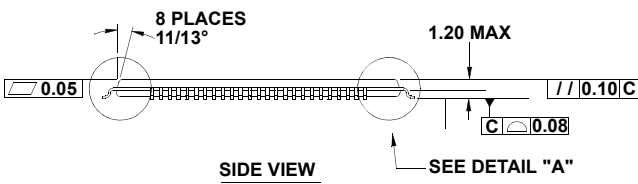
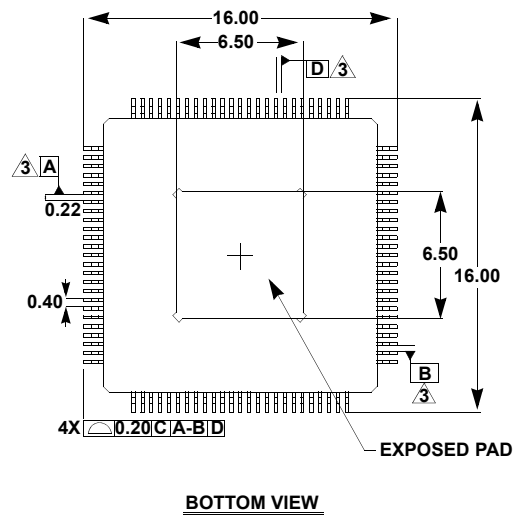
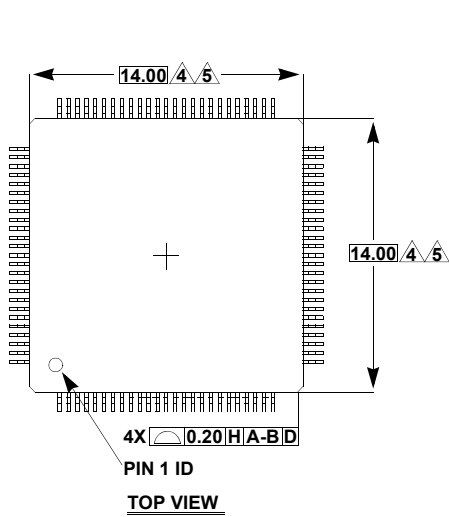


## Package Outline Drawing

Q128.14x14B

128 LEAD THIN PLASTIC QUAD FLATPACK EXPOSED PAD PACKAGE (TQFP-EP)

Rev 2, 7/11



### NOTES:

- All dimensioning and tolerancing conform to ANSI Y14.5-1982.
- Datum plane **H** located at mold parting line and coincident with lead, where lead exits plastic body at bottom of parting line.
- Datums **A-B** and **D** to be determined at centerline between leads where leads exit plastic body at datum plane **H**.
- Dimensions do not include mold protrusion. Allowable mold protrusion is 0.254mm.
- These dimensions to be determined at datum plane **H**.
- Package top dimensions are smaller than bottom dimensions and top of package will not overhang bottom of package.
- Does not include dambar protrusion. Allowable dambar protrusion shall be 0.08mm total at maximum material condition. Dambar cannot be located on the lower radius or the foot.
- Controlling dimension: millimeter.
- This outline conforms to JEDEC publication 95 registration MS-026, variation BHB-HU.
- Dimensions in ( ) are for reference only.
- Max allowable die thickness to be assembled in this package family is 0.50mm.
- This outline is not yet JEDEC registered.
- A1 is defined as the distance from the seating plane to the lowest point of the package body.
- Exposed die pad shall be coplanar with bottom of package within 0.05mm.
- Metal area of exposed die pad shall be within 0.30mm of the nominal die pad size.
- Corner chamfer of exposed die pad shall be within 1.0mm.